



Material Content Data Sheet



Sales Product Name		IPD65R420CFDA		Issued		25. September 2017		
MA#		MA001016862						
Package		PG-TO252-3-313		Weight*		319.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.901	1.53	1.53	15315	15315
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		460	
	non noble metal	copper	7440-50-8	147.096	45.99	46.05	459700	460298
	non noble metal	aluminium	7429-90-5	0.537	0.17	0.17	1678	1678
wire	non noble metal	aluminium	7429-90-5	0.537	0.17	0.17	1678	1678
encapsulation	organic material	carbon black	1333-86-4	1.389	0.43		4342	
	plastics	epoxy resin	-	24.312	7.60		75980	
	inorganic material	silicondioxide	60676-86-0	113.226	35.38	43.41	353850	434172
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11688	11688
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4439	4450
solder	non noble metal	tin	7440-31-5	0.079	0.02		248	
	noble metal	silver	7440-22-4	0.099	0.03		310	
	non noble metal	lead	7439-92-1	3.785	1.18	1.23	11830	12388
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.99	6.00	59933	60011
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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